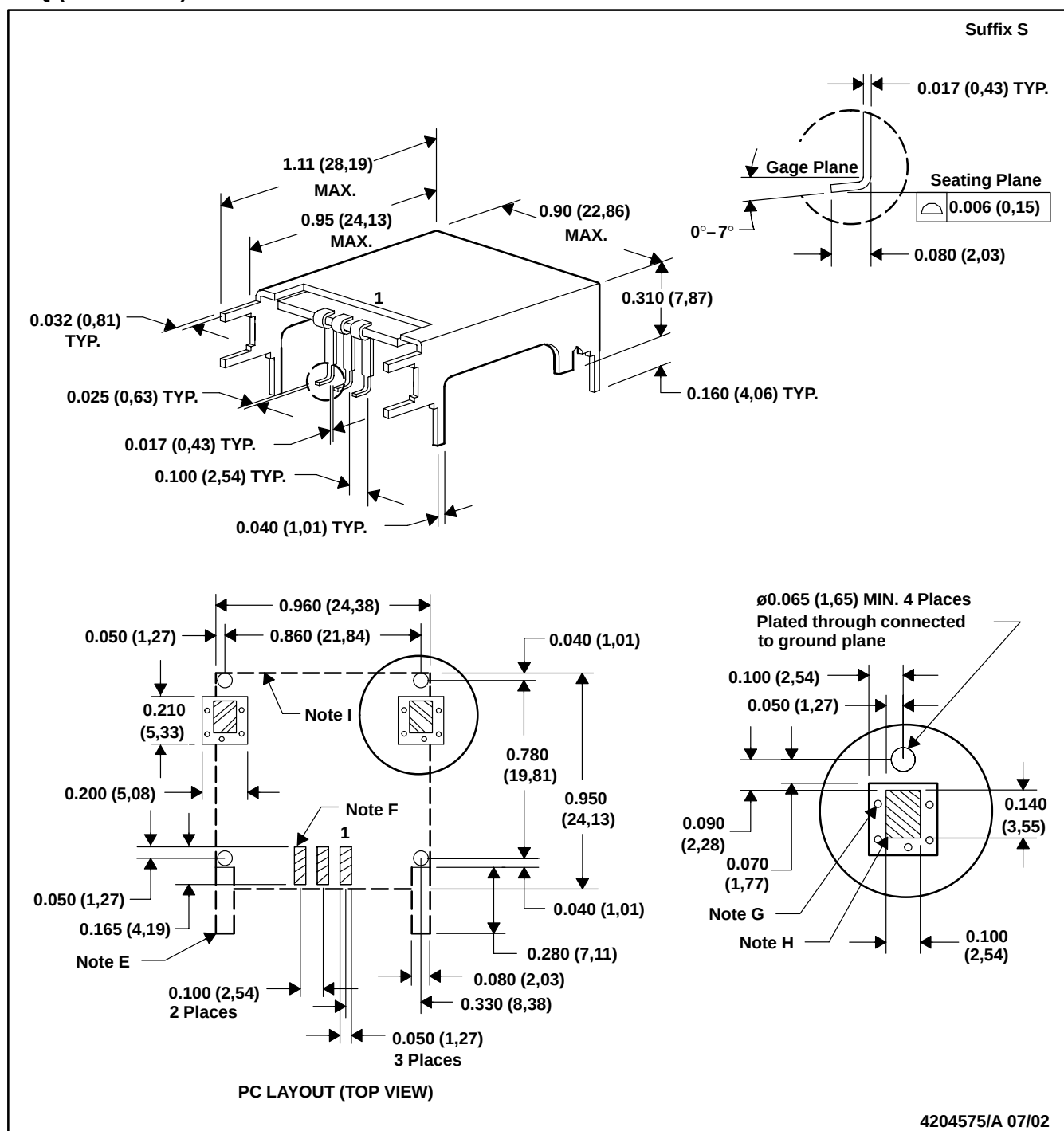


EFQ (R-MSIP-T3)

METAL SINGLE-IN-LINE MODULE



NOTES: A. All linear dimensions are in inches (mm).
 B. This drawing is subject to change without notice.
 C. 2 place decimals are ± 0.030 ($\pm 0,76$ mm).
 D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 E. Recommended mechanical keep out area.
 F. Power pin connections should utilize two or more vias per input, ground and output pin.

G. Vias are recommended to improve copper adhesion.
 H. Solder mask openings to copper island for solder joints to mechanical pins. Electrically connect case to ground plane.
 I. Case outline reference

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